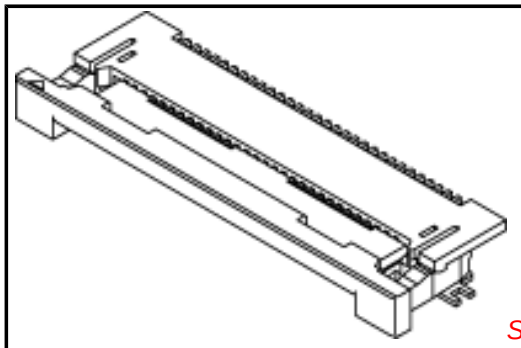
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Part Number: 0541324362
Status: Active
Overview: ffc_fpc_smt
Description: 0.50mm (.020") Pitch FFC/FPC Connector, Right Angle, SMT, ZIF, Bottom Contact Style, 43 Circuits, 0.1µm (4µ") Gold (Au) Contact Plating



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Product Specification PS-54132-061 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

UL	E29179

General

Product Family	FFC/FPC Connectors
Series	54132
Overview	ffc_fpc_smt
Product Name	N/A

Physical

Circuits (Loaded)	43
Color - Resin	Black, Natural
Contact Position	Bottom
Durability (mating cycles max)	20
Entry Angle	90° Angle
Flammability	94V-0
Mated Height (in)	0.079 In
Mated Height (mm)	2.00 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Plating min: Mating (µin)	4
Plating min: Mating (µm)	0.1
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	N/A
Temperature Range - Operating	-20°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Halogen-Free

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

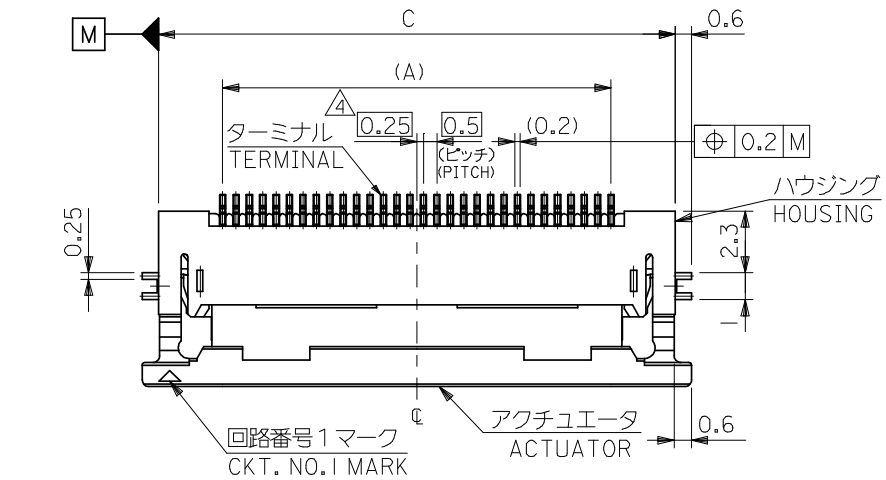
Please visit the Contact Us section for any non-product compliance questions.

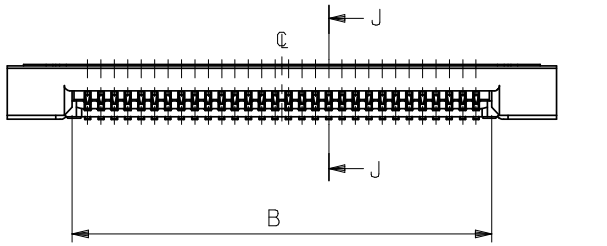
Search Parts in this Series
54132Series

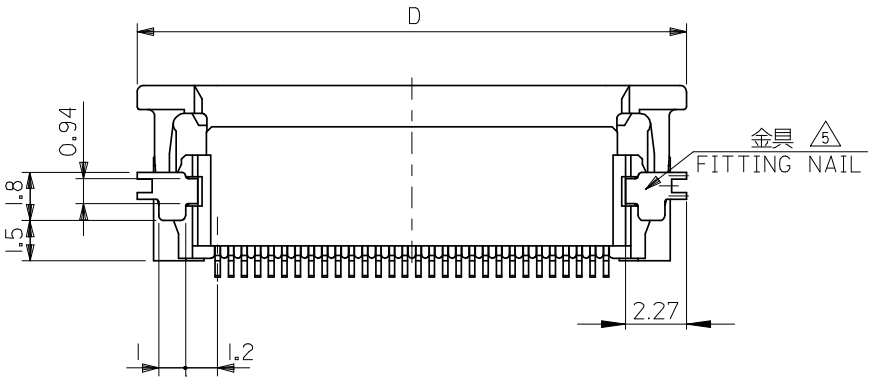
Product Specification	PS-54132-061, RPS-54132-071, RPS-54132-076
Sales Drawing	SD-54132-064

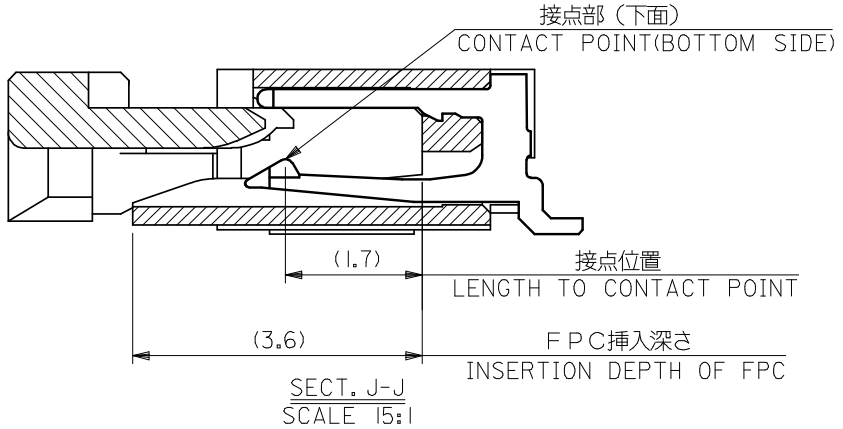
This document was generated on 06/07/2010

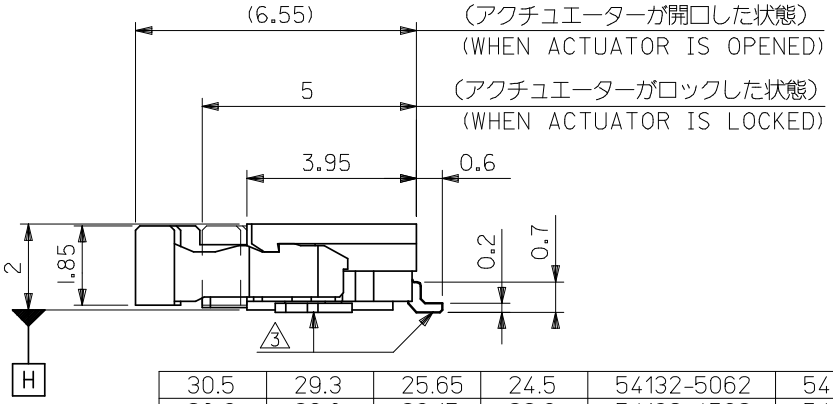
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D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL. NO.	CKT.
30.5	29.3	25.65	24.5	54132-5062	54132-5068	50
28.0	26.8	23.15	22.0	54132-4562	54132-4568	45
27.0	25.8	22.15	21.0	54132-4362	54132-4368	43
25.5	24.3	20.65	19.5	54132-4062	54132-4068	40
24.5	23.3	19.65	18.5	54132-3862	54132-3868	38
23.5	22.3	18.65	17.5	54132-3662	54132-3668	36
23.0	21.8	18.15	17.0	54132-3562	54132-3568	35
22.5	21.3	17.65	16.5	54132-3462	54132-3468	34
22.0	20.8	17.15	16.0	54132-3362	54132-3368	33
21.5	20.3	16.65	15.5	54132-3262	54132-3268	32
20.5	19.3	15.65	14.5	54132-3062	54132-3068	30

REVISED
EC NO: J2008-4308 2008/06/27
DRWN:MNABEI 2008/06/30
CH'KD:THARUYAMA 2008/06/30
APPR:NUKITA 2008/06/30
DESCRIPTION
REV
M

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: M.UMEDA DATE: 2004/09/27
CHECKED BY: K.TOYODA DATE: 2004/09/27
APPROVED BY: N.UKITA DATE: 2004/09/27

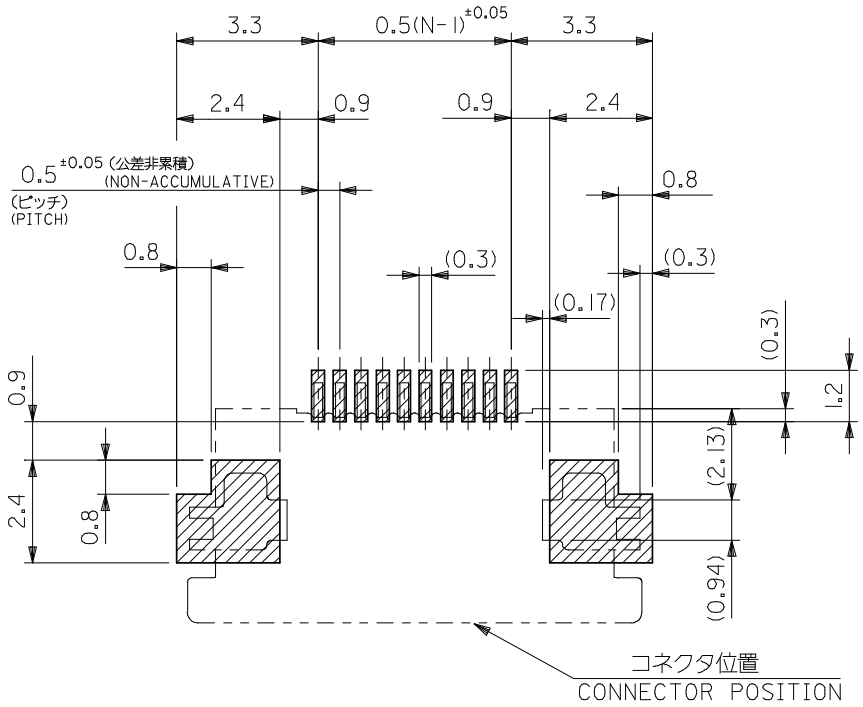
TITLE: 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)

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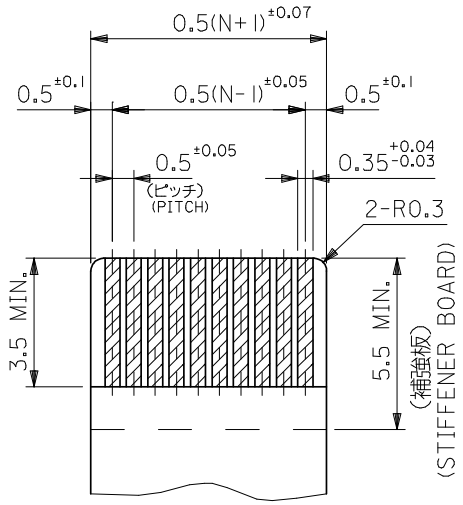
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-54132-064
SHEET NO.: 1 OF 4

SIZE A3

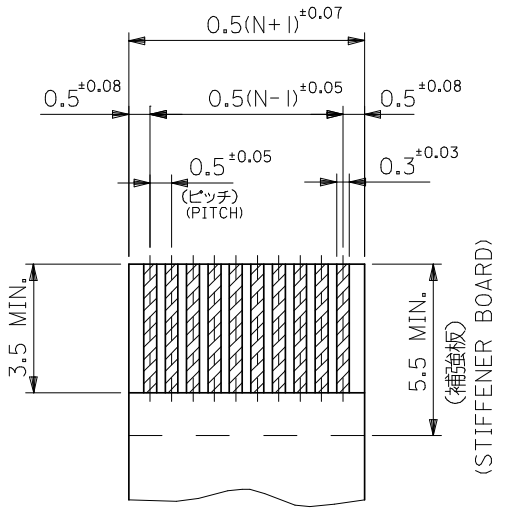
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参考基板レイアウト
RECOMMENDED PC BOARD PATTERN DIMENSON(REF.)
(マウント面)
(MOUNTING SIDE)



適合ＦＰＣ推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)



適合ＦＦＣ推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)

注記
NOTES

1．使用材料
MATERIAL

ハウジング HOUSING	：46ナイロン，UL94V−0 :46NYLON
アクチュエーター ACTUATOR	：PPS，UL94V−0 :PPS
ターミナル	:金メッキ コンタクト部 0.1 MICRO METER MIN. テ ー ル 部 0.05 MICRO METER MIN. :ニッケル下地 1.0 MICRO METER MIN.
TERMINAL	:GOLD PLATING CONTCT PORTION:0.1 MICRO METER MIN. TAIL PORTION:0.05 MICRO METER MIN. :NI-PLATING:0.1 MICRO METER MIN.
金具	:リン青銅（t=0．2）、錫メッキ 1．0~3．0 MICRO METER MIN. ニッケル下地 1．0~3．0 MICRO METER MIN.
FITTING NAIL	:PHOS-BRO,TIN-PLATE 1．0~3．0 MICRO METER MIN. OVER NICKEL 1．0~3．0 MICRO METER MIN.

2．エンボステープ梱包時は、アクチュエーターがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54132-**69 SHOULD BE LOCKED.

3 ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向0．1MAX．下方向0．15MAX．とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAIL FROM H UPPER DIRECTION:0.1 MAX.,LOWER DIRECTION:0.15MAX.

4 偶数極に適用
APPLY FOR EVEN CIRCUIT.

5 パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

6. 本製品は54132−**61に対するニッケルバリア品である．
THIS PRODUCT IS Ni-Barrier OF 54132-**61.

FPC/FFCについて：
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメーターまたは50マイクロメーター
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL : 35 micrometer or 50 micrometer

FPCについて：
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED
E EC NO: J2008-4308 2008/06/27
DRWN:MNABEI 2008/06/30
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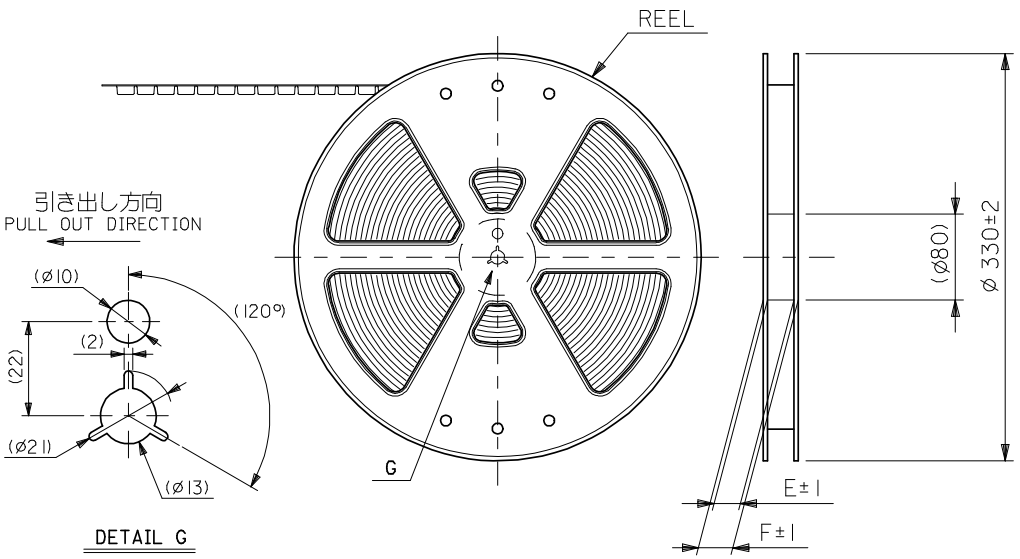
GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

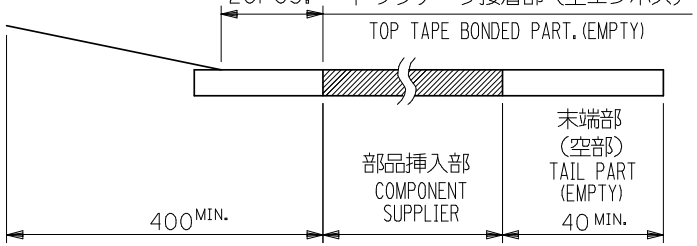
DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	M.UMEDA 2004/09/27
CHECKED BY / DATE	K.TOYODA 2004/09/27
APPROVED BY / DATE	N.UKITA 2004/09/27
TITLE	0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)
	MOLEX INCORPORATED
MATERIAL NO.	SEE SHEET 1
DOCUMENT NO.	SD-54132-064
SHEET NO.	2 OF 4
SIZE	A3

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DETAIL G

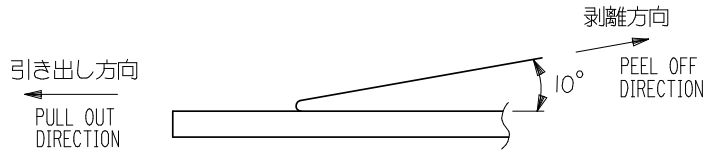
引き出し方向
PULL OUT DIRECTION



NOTES

1. 梱包数量：１５００個／リール
   NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

3. トップテープの剥離強度： 0.1N ～ 1.3N{10gf ～ 130gf}
   （剥離方向は下図参照）
   尚、本規格値は出荷時に適用。（但し、輸送時に剥離が発生しないこと。）
   PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N{10gf ～ 130gf}
   (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG,)
   THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
   PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



5. 材料　キャリアテープ：ポリプロピレン（ＰＰ）
   トップテープ：ＰＥＴ，ＰＥ，ＰＥＦ
   リール：ポリスチレン（ＰＳ）<リサイクル材を含む>

   MATERIAL CARRIER TAPE:POLYPROPYLENE
   TOP TAPE:PET,PE,PEF
   REEL:POLYSTYREN(PS)
   <RECYCLE MATERIAL CONTAINED>

6. 本製品は54132−＊＊61に対するニッケルバリア品である．
   THIS PRODUCT IS Ni-Barrier OF 54132-**61.

REVISED			
EC NO: J2008-4308	2008/06/27		
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APPR:NUKITA			

DESCRIPTION

REV E

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±---
10 OVER 30 UNDER	±---
30 OVER	±---
ANGULAR	±--- °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: ---	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: M.UMEDA	DATE: 2004/09/27		
CHECKED BY: K.TOYODA	DATE: 2004/09/27		
APPROVED BY: N.UKITA	DATE: 2004/09/27		
MATERIAL NO.: SEE SHEET 4			

TITLE: 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)

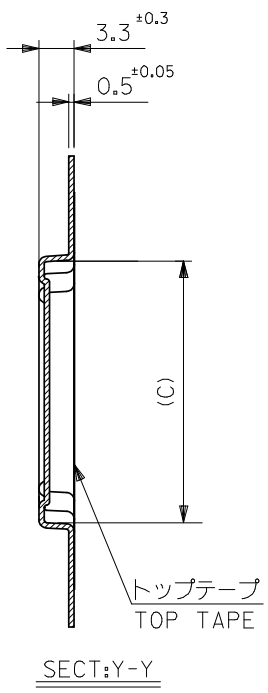
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DOCUMENT NO.: SD-54132-064

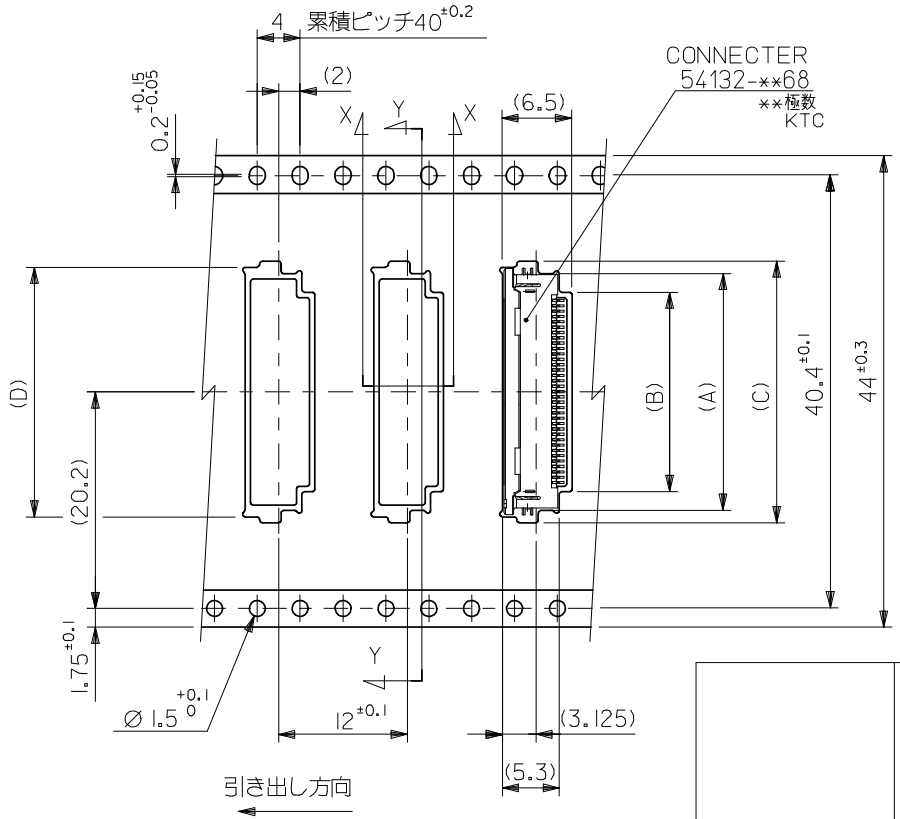
SHEET NO.: 3 OF 4

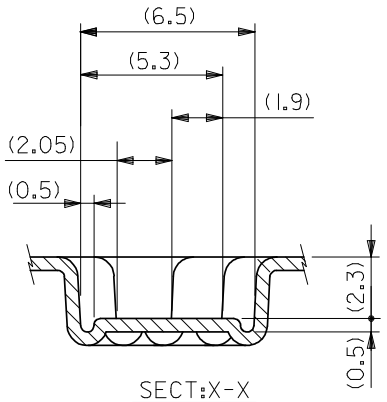
SIZE A3

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SECT:Y-Y





SECT:X-X
(SCALE 5:1)

			30.8	31.9	26.1	29.6	54132-5062	50
			28.3	29.4	23.6	27.1	54132-4562	45
			27.3	28.4	22.6	26.1	54132-4362	43
			25.8	26.9	21.1	24.6	54132-4062	40
			24.8	25.9	20.1	23.6	54132-3862	38
44	49.4	45.4	23.8	24.9	19.1	22.6	54132-3662	36
			23.3	24.4	18.6	22.1	54132-3562	35
			22.8	23.9	18.1	21.6	54132-3462	34
			22.3	23.4	17.6	21.1	54132-3362	33
			21.8	22.9	17.1	20.6	54132-3262	32
			20.8	21.9	16.1	19.6	54132-3062	30
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO. (EMBOSS PKG)	CKT.

REVISED
E1 EC NO: J2008-4308 2008/06/27
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APPR:NUKITA 2008/06/30
DESCRIPTION
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GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±---
10 OVER 30 UNDER	±---
30 OVER	±---
ANGULAR	±--- °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: M.UMEDA DATE: 2004/09/27
CHECKED BY: K.TOYODA DATE: 2004/09/27
APPROVED BY: M.UMEDA DATE: 2004/09/27
MATERIAL NO.: SEE TABLE

TITLE: 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)

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DOCUMENT NO.: SD-54132-064
SHEET NO.: 4 OF 4
SIZE: A3

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